SMBJ5955B-TPS01
SMBJ5956B-TPS01

1.5 Watt
Surface Mount
Silicon
Zener Diodes

Features

- Surface Mount Application
- Low Inductance,Low Profile Mounting
- Glass Passivated Junction
- Available on Tape and Reel
- Lead free and RoHs Compliant

Mechanical Data

- CASE: JEDEC DO-214AA molded Surface Mountable
- Terminals solderable per MIL-STD-750, Method 2026
- Polarity is indicated by cathode band.
- Packaging: Standard 12mm Tape (see EIA 481)
- Maximum temperature for soldering: 260°C for 10 seconds.
- For surface mount applications with flame retardent epoxy Meeting UL94V-0

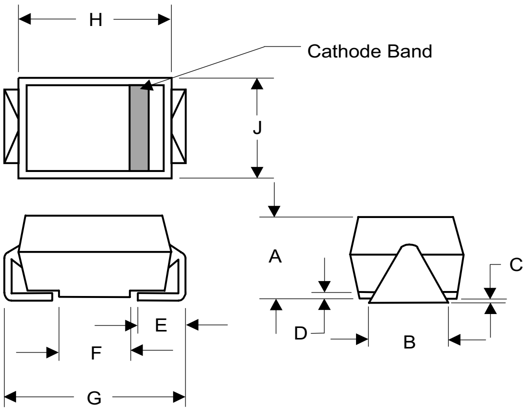
Maximum Ratings @ 25°C Unless Otherwise Specified

Forward Current	I_F	See Table 1	
Maximum Forward Voltage	V_F	1.5V	(Note: 1)
Steady State Power Dissipation	$P_{(AV)}$	1.5W	(Note: 2)
Operation and Storage Temperature	T_J, T_{STG}	-55°C to +150 °C	

NOTES:

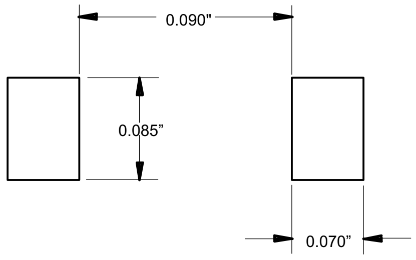
1. Forward Current @ 200mA.
2. Mounted on 5.0mm^2 (.013mm thick) land areas. Lead temperature at T_L=75°C

DO-214AA
(HSMB) (Round Lead)



DIM	INCHES MIN	INCHES MAX	MM MIN	MM MAX	NOTE
A	.078	.116	1.98	2.95	
B	.075	.089	1.90	2.25	
C	.002	.008	.05	.20	
D	-----	.02	-----	.51	
E	.035	.055	.90	1.40	
F	.065	.091	1.65	2.32	
G	.205	.224	5.21	5.69	
H	.160	.180	4.06	4.57	
J	.130	.155	3.30	3.94	

SUGGESTED SOLDER
PAD LAYOUT



SMBJ5955B-TPS01
SMBJ5956B-TPS01

ELECTRICAL CHARACTERISTICS (T_L=30°C unless otherwise noted) (V_F=1.5Volts Max @ I_F=200mAdc for all types.)

Device	Nominal Zener Voltage Vz @ I_{ZT} volts (Note 1.)	Test current I_{ZT} mA	Maximum Zener Impedance (Note 2.)			Max reverse Leakage Current		Maximum DC Zener Current I_{ZM} mAdc	Device Marking Code
			Z_{ZT} @ I_{ZT} Ohms	Z_{Zk} @ I_{ZK} Ohms @	I_{ZK} mA	I_R µA @	V_R Volts		
SMBJ5955B-TPS01	180	2.1	900	7000	0.25	1	136.8	8	H55B
SMBJ5956B-TPS01	200	1.9	1200	8000	0.25	1	152	7	H56B

Tolerance and voltage designation - The type numbers listed indicate a tolerance of +/- 5%.

IMPORTANT NOTICE

Edcon-Components reserves the right to make changes without further notice to any product herein to make corrections, modifications , enhancements , improvements , or other changes . Edcon-Components does not assume any liability arising out of the application or use of any product described herein; neither does it convey any license under its patent rights ,nor the rights of others . The user of products in such applications shall assume all risks of such use and will agree to hold *EdconComponents* and all the companies whose products are represented on our website, harmless against all damages.

APPLICATIONS DISCLAIMER

Products offer by *Edcon-Components* are not intended for use in Medical, Aerospace or Military Applications.